APPLICANT: FANVIL TECHNOLOGY CO., LTD.
ADDRESS: LEVEL 3, BLOCK A, GAOXINQI BUILDING, ANHUA INDUSTRIAL PARK, QIANJIN 1 ROAD, 35TH DISTRICT, BAO'AN, SHENZHEN, 518101 P.R. CHINA.

MANUFACTURE : FANVIL TECHNOLOGY CO., LTD.
ADDRESS: LEVEL 3, BLOCK A, GAOXINQI BUILDING, ANHUA INDUSTRIAL PARK, QIANJIN 1 ROAD, 35TH DISTRICT, BAO'AN, SHENZHEN, 518101 P.R. CHINA.

Report on the submitted sample said to be IP VIDEO PHONE BRAND NAME: N/A MODEL: C600

Test Required: 1)As required by client to determine the Lead,Cadmium,Mercury,Chrimium and Bromine content in the submitted sample.

Test Method:

Testing Item	Testing method	Limit
Lead (Pb)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES	1000ppm
Cadmium (Cd)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES	100ppm
Mercury (Hg)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-OES	1000ppm
Hexavalent Chromium (Cr6+)	With reference to IEC62321/2nd CDV (111/95/CDV) ICP-VIS	1000ppm
Polybrominated Biphenyls (PBBs)	With reference to IEC62321/2nd CDV (111/95/CDV) GC-MS	1000ppm
Polybrominated Diphenylethers (PBDEs)	With reference to IEC62321/2nd CDV (111/95/CDV) GS-MS	1000ppm

Results : Please refer to next pages

Conclusion : When tested as specified,the results shown on the report do not exceed the limit in commission decision of 8 June 2011 Directive 2011/65/EU (RoHS 2) on the restriction of the use of certain hazardous substances in electrical and electronic equipment.All data in this report is provided by the manufacture.

Signed for Shenzhen PZD Technology Co.,Ltd.

Mark Yan Manager

APPROVED PZD Technology

RESULT SUMMARY

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
1.1	MLCC-POWDER NPO	ND	ND	ND	ND	ND	Fulfilled
1.2	MLCC-Ni Paste	ND	ND	ND	ND	ND	Fulfilled
1.3	MLCC-Cu Paste	ND	ND	ND	ND	ND	Fulfilled
1.4	MLCC-Ni Plating	ND	ND	ND	ND	ND	Fulfilled
1.5	MLCC-Sn Plating	ND	ND	ND	ND	ND	Fulfilled
2.1	MLCC-POWDER X7R	ND	ND	ND	ND	ND	Fulfilled
2.2	MLCC-Ni Paste	ND	ND	ND	ND	ND	Fulfilled
2.3	MLCC-Cu Paste	ND	ND	ND	ND	ND	Fulfilled
2.4	MLCC-Ni Plating	ND	ND	ND	ND	ND	Fulfilled
2.5	MLCC-Sn Plating	ND	ND	ND	ND	ND	Fulfilled
3.1	MLCC-POWDER Y5V	ND	ND	ND	ND	ND	Fulfilled
3.2	MLCC-Ni Paste	ND	ND	ND	ND	ND	Fulfilled
3.3	MLCC-Cu Paste	ND	ND	ND	ND	ND	Fulfilled
3.4	MLCC-Ni Plating	ND	ND	ND	ND	ND	Fulfilled
3.5	MLCC-Sn Plating	ND	ND	ND	ND	ND	Fulfilled
4.1	MLCC-POWDER X5R	ND	ND	ND	ND	ND	Fulfilled
4.2	MLCC-Ni Paste	ND	ND	ND	ND	ND	Fulfilled
4.3	MLCC-Cu Paste	ND	ND	ND	ND	ND	Fulfilled
4.4	MLCC-Ni Plating	ND	ND	ND	ND	ND	Fulfilled
4.5	MLCC-Sn Plating	ND	ND	ND	ND	ND	Fulfilled
5	Resistor	ND	ND	ND	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
6	AVX CAP	---	---	---	---	---	Declaration
7	Resistor array	ND	ND	372	ND	ND	Fulfilled
8	SMD Resistor	ND	ND	457	ND	ND	Fulfilled
9	Diode SS14/SMA S210	ND	ND	ND	ND	ND	Fulfilled
10	Diode MWZZ5V6	ND	ND	ND	ND	ND	Fulfilled
11	BEAD	ND	ND	ND	ND	ND	Fulfilled
12.1	POWER INDUCTOR-Copper wire	ND	ND	ND	ND	---	Fulfilled
12.2	Epoxy Resin	ND	ND	ND	ND	ND	Fulfilled
12.3	Ferrite Core	ND	ND	ND	ND	ND	Fulfilled
12.4	Sn	ND	ND	25	ND	---	Fulfilled
12.5	Ink	ND	ND	ND	ND	ND	Fulfilled
13	MOS IC A03401	---	---	---	---	---	Declaration
14	Transistor S850 LMBT3904LT1G	ND	ND	ND	ND	ND	Fulfilled
15	CPU BCM SERIES	---	---	---	---	---	Declaration
16	SDRAM IC	---	---	---	---	---	Declaration
17	FLASH IC	---	---	---	---	---	Declaration
18	DC-DC IC	ND	ND	ND	ND	ND	Fulfilled
19	AMP IC	ND	ND	ND	ND	ND	Fulfilled
20.1	POE POWER-Gold wire	ND	ND	ND	ND	ND	Fulfilled
20.2	Die Paste	ND	ND	9	ND	---	Fulfilled
20.3	Leadframe	ND	ND	ND	ND	ND	Fulfilled
20.4	Epoxy Ccmpound	ND	ND	151	ND	---	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
21	RESET IC ANALOG SWITCH	ND	ND	ND	ND	ND	Fulfilled
22.1	NET TRANSFORM M3088NL/M3336NL -older bar	ND	ND	43	ND	ND	Fulfilled
22.2	Body	ND	ND	ND	ND	ND	Fulfilled
22.3	Metal wire	ND	ND	ND	ND	ND	Fulfilled
22.4	Ferrite bead	ND	ND	ND	ND	ND	Fulfilled
23	FPC CABLE	ND	ND	67	ND	ND	Fulfilled
24	FPC CONNECTOR	ND	ND	6	ND	ND	Fulfilled
25	EC CAP	ND	ND	ND	ND	ND	Fulfilled
26	CRYSTAL	ND	ND	ND	ND	ND	Fulfilled
27.1	DIP TERMINALS-LCP	ND	ND	6	ND	ND	Fulfilled
27.2	PA6T	ND	ND	ND	ND	ND	Fulfilled
27.3.1	Copper	ND	ND	24	ND	---	Fulfilled
27.3.2	Au Plating	ND	ND	36	ND	---	Fulfilled
27.3.3	Ni Plating	ND	9	123	ND	---	Fulfilled
27.4	Copper C2680	ND	ND	33	ND	ND	Fulfilled
27.5	Copper C5191	ND	ND	9	ND	ND	Fulfilled
28	SWITCH OF SPRING	ND	ND	ND	ND	ND	Fulfilled
29.1	PCB –KB6160	ND	ND	10	ND	ND	Fulfilled
29.2	INK	ND	ND	ND	ND	ND	Fulfilled
29.3	MARKING INK	ND	ND	ND	ND	ND	Fulfilled
29.4	SOLDER	ND	ND	201	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
29.5	PCB	ND	ND	5	ND	---	Fulfilled
30	PCB (KEY) KB-5150	ND	ND	15	ND	ND	Fulfilled
31	NXP IC	---	---	---	---	---	Declaration
32	LED	ND	ND	ND	ND	ND	Fulfilled
33	ENCLOSURE PLASTIC	ND	ND	ND	ND	ND	Fulfilled
34	Rubber part	ND	ND	ND	ND	ND	Fulfilled
35.1	616E SOCKET-PVC	ND	ND	ND	ND	ND	Fulfilled
35.2	PVC	ND	ND	ND	ND	ND	Fulfilled
35.3	Masterbatches	ND	ND	ND	ND	ND	Fulfilled
35.4	Copper	ND	ND	9	ND	---	Fulfilled
36	MIC	ND	ND	ND	ND	ND	Fulfilled
37	MIC Rubber	ND	8	35	ND	ND	Fulfilled
38.1	SPEAKER-PCB	ND	ND	4	ND	ND	Fulfilled
38.2	PAPER	ND	ND	ND	ND	ND	Fulfilled
38.3	NdFeB Ferrtie	ND	ND	ND	ND	ND	Fulfilled
38.4	Metal cover	ND	ND	ND	ND	ND	Fulfilled
38.5	Enclosure plastic stand	ND	ND	ND	ND	ND	Fulfilled
38.6	Glue	ND	ND	ND	ND	ND	Fulfilled
38.7	Copper wire	ND	ND	ND	ND	ND	Fulfilled
38.8	PET sheet	ND	ND	ND	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
38.9	Metal Plating	ND	ND	ND	ND	---	Fulfilled
39	Dustproof Net	ND	ND	ND	ND	ND	Fulfilled
40	EVA	ND	ND	ND	ND	ND	Fulfilled
41	METAL BLOCK	ND	ND	ND	ND	---	Fulfilled
42	RUBBER OF HEADSET	ND	ND	ND	ND	ND	Fulfilled
43.1	LCD MODULE-PCB	ND	ND	ND	ND	ND	Fulfilled
43.2	LED TOP	ND	ND	ND	ND	ND	Fulfilled
43.3	RESISTOR	ND	ND	ND	ND	ND	Fulfilled
43.4	Proliferation of film	ND	ND	ND	ND	ND	Fulfilled
43.5	Reflector film	ND	ND	ND	ND	ND	Fulfilled
44	UNIFOAM RSF	ND	ND	ND	ND	ND	Fulfilled
45	FOOTPAD COVER OF LCD PANEL	ND	ND	ND	ND	ND	Fulfilled
46.1	SCREW	ND	ND	ND	ND	---	Fulfilled
46.2	SCREW	ND	ND	ND	ND	---	Fulfilled
47	PROTECTIVE FILM	ND	ND	ND	ND	ND	Fulfilled
48	LABEL	ND	ND	ND	ND	ND	Fulfilled
49	PACKAING BAG	ND	ND	ND	ND	ND	Fulfilled
50.1	HEADSET WIRE-COPPER	ND	ND	ND	ND	---	Fulfilled
50.2	PVC	ND	ND	ND	ND	ND	Fulfilled

Note:
ND=Not Detected ,less than the value of Detection limit
Ppm=mg/kg,based on the dry weight of tested sample

	Detected content (grade) – See below marks						
	Parts description	Cr6+	Cd	Pb	Hg	Br	Conclusion
51.1	NETCABLE -PVC	ND	ND	ND	ND	ND	Fulfilled
51.2	WIRE	ND	ND	ND	ND	---	Fulfilled
52.1	PAPER BOARD	ND	ND	ND	ND	ND	Fulfilled
52.2	PAPER	ND	ND	11	ND	ND	Fulfilled
53	CATOON BOX	ND	ND	7	ND	ND	Fulfilled

Remark
1.1 Refer to client information SGS:KA/2014/70941
1.2 Refer to client information SGS:KA/2014/70947
1.3 Refer to client information SGS:KA/2014/70949
1.4 Refer to client information SGS:KA/2014/70951
1.5 Refer to client information SGS:KA/2014/70952
2.1 Refer to client information SGS:KA/2014/70938
2.2 Refer to client information SGS:KA/2014/70945
2.3 Refer to client information SGS:KA/2014/70949
2.4 Refer to client information SGS:KA/2014/70951
2.5 Refer to client information SGS:KA/2014/70952
3.1 Refer to client information SGS:KA/2014/70940
3.2 Refer to client information SGS:KA/2014/70946
3.3 Refer to client information SGS:KA/2014/70949
3.4 Refer to client information SGS:KA/2014/70951
3.5 Refer to client information SGS:KA/2014/70952
4.1 Refer to client information SGS:KA/2014/70939
4.2 Refer to client information SGS:KA/2014/70945
4.3 Refer to client information SGS:KA/2014/70949
4.4 Refer to client information SGS:KA/2014/70951
4.5 Refer to client information SGS:KA/2014/70952
5 Refer to client information SGS:SHAEC1324970319
6 Refer to client information from DECLARATION LETTER
7 Refer to client information SGS:SHAEC1324969629
8 Refer to client information SGS:SHAEC1324970313
9 Refer to client information SGS:SHAEC1103797802
10 Refer to client information CTI:RLSZD000857290002

11 Refer to client information SGS:CE/2014/A2589
12.1 Refer to client information SGS:CE/2014/41140
12.2 Refer to client information SGS:CANEC1416971801
12.3 Refer to client information CTI:SCL01G007849001E
12.4 Refer to client information SGS:CANEC1410296601
12.5 Refer to client information SGS:SHAEC1403535705
13. Refer to client information from DECLARATION LETTER
14 Refer to client information SGS:CKGEC1400013701
15 Refer to client information from DECLARATION LETTER
16 Refer to client information from DECLARATION LETTER
17 Refer to client information from DECLARATION LETTER
18 Refer to client information SGS:SHAEC1400833311 A01
19. Refer to client information SGS:SHAEC1324000609 A01
20.Refer to client information from DECLARATION LETTER
21.Refer to client information SGS:SHAEC1321669502
22.1 Refer to client information SGS:CANEC1420087301
22.2 Refer to client information SGS:CANEC1401363201
22.3 Refer to client information SGS:CANEC1421467907
22.4 Refer to client information SGS:CANEC1403165305 A01
23. Refer to client information SGS:CANEC1102359106
24. Refer to client information SGS:CANEC1102359102
25. Refer to client information SGS:CANEC1403103801
26. Refer to client information SGS:CANEC1420970506
27.1 Refer to client information SGS:CANEC1400397701
27.2 Refer to client information SGS:CANEC1400258801
27.3.1 Refer to client information CTI:RHS01G003645001

27.3.2 Refer to client information SGS:CANEC1402507401
27.3.3 Refer to client information SGS:CANEC1402502901
27.4 Refer to client information SGS:CANEC150027302
27.5 Refer to client information SGS:CANEC1500027306
28. Refer to client information HTW:TRC14030037/CH
29.1 Refer to client information SGS:CANEC1411243501
29.2 Refer to client information CTI:RHS01F013843003
29.3 Refer to client information CTI:RHS05G016677014
29.4 Refer to client information SGS:CANEC1402433301
29.5 Refer to client information SGS:CANEC1410890302
30. Refer to client information SGS: CANEC1407696802
31. Refer to client information from DECLARATION LETTER
32 Refer to client information CTI:RHS03G001003
33 Refer to client information SGS:CANML1407334907
34 Refer to client information SGS:CANML1318583602
35.1 Refer to client information CTI:SCL01G047600001C
35.2 Refer to client information CTI:SCL01G047600002C
35.3 Refer to client information SGS:CANAUTO1203308002 A01
35.4 Refer to client information SGS:CANEC1408189101
36. Refer to client information AOV:A001R140604071002
37. Refer to client information SGS:CANEC1401509117
38.1 Refer to client information SGS:CANEC1402544101
38.2 Refer to client information SGS:SHAEC1404486901
38.3 Refer to client information SGS:CANEC1402991701
38.4 Refer to client information CTI:SCL01G06209800101
38.5 Refer to client information SGS:CANEC1413996201

38.6 Refer to client information SGS:CE/2014/95322
38.7 Refer to client information CTI:RHS01G003468003E
38.8 Refer to client information SGS:CE/2014/44588
38.9 Refer to client information SCTS:RC1404129
39 Refer to client information SGS:CANEC1401509109
40 Refer to client information SGS:CANEC1419406102
41 Refer to client information SGS:CANEC1306444502
42 Refer to client information HCT:SZC14022581781-11
43.1 Refer to client information SGS:CANEC1411328905
43.2 Refer to client information SGS:CANEC1417913701
43.3 Refer to client information CTI:RHS05G010309002E
43.4 Refer to client information SGS:CANEC1419886802
43.5 Refer to client information SGS:NGBEC1401816301
44 Refer to client information SGS:SHAEC1408587601
45 Refer to client information SGS:SHAEC1417815101
46.1 Refer to client information SGS:CANEC1402483504
46.2 Refer to client information SGS:CANEC1402483503
47. Refer to client information SGS:CANEC1415268903
48. Refer to client information SGS:CANEC1413144301
49. Refer to client information SGS:CANEC1404263521
50.1 Refer to client information CTI:SCL01G065845002
50.2 Refer to client information CTI:SCL01G065845001
51.1 Refer to client information SGS:CANEC1416139403 A01
51.2 Refer to client information SGS:CANEC1313752804
52.1 Refer to client information SGS:CANML1404152001
52.2 Refer to client information SGS:CANEC1401146702

53. Refer to client information SGS:CANEC1415598303

APPENDIX I

DECLARATION LETTER FROM AVX

AVX CORPORATION
A KYOCERA GROUP COMPANY

18 June 2014

REACH SVHC Statement

Dear Customer:

On June 1, 2007, the European Commission promulgated new legislation that covers the registration, evaluation, authorization and restriction of chemical within the European Union community. This new regulation is commonly known as REACH, an acronym for **R**egistration, **E**valuation and **A**uthorization of **Ch**emicals.

AVX supports the underlying goals of REACH, which are consistent with our own commitment to promote the responsible manufacturing, use and handling of chemicals. We are in contact with all suppliers to AVX and will meet the pre-registration deadline for all chemical substances in quantities greater than one metric ton.

AVX understands the critical nature of our supply chain and can assure you that there will not be any disruptions in the continued delivery of our products. AVX will seamlessly transition through this process as we have in the past with other similar legislation.

Additionally, after careful review of the legislation and specifically the definition of an "article" as defined in EC Regulation 1907/2006, Title II, Chapter 1, Article 7.1(a) & (b), it is AVX's current view that the products AVX sells to you would be considered as "articles". However, in light of the definition in § 7.1(b) which requires registration of an article only if it contains a regulated substance that ***"is intended to be released under normal or reasonably foreseeable conditions of use,"*** AVX's analysis is that such products constitute non-registrable articles for their intended and anticipated use.

The product families listed below contain one of the following lead oxides published in the 19 December 2012 ECHA SVHC Candidate List at or greater than 0.1% of total weight:

Lead monoxide (CAS 1317-36-8),
- ATC 600 series,
- ADxxC…,
- ANxxC…,
- APxxA…,
- Automotive NPO MLCCs and arrays using ELV Exemption 10(c) (Send list to verify),
- CDRBX series,
- DIPGuard (MD…),
- Discoidal capacitors (DC…),
- Molded Axial (MAxxxA…),
- Molded Radial (MRxxxA…),

NPO Feedthrus (WxFxxA…),
PBRC…,
Some leaded military parts (Send list to verify).

Lead titanium zirconium oxide (CAS 12626-81-2),
Automotive NPO MLCCs and arrays using ELV Exemption 10(c) (Send list to verify),
Some leaded military parts (Send list to verify).

Lead tetraoxide - orange lead - (CAS 1314-41-6)
PBRV…,
PRQC…,
SMPS (Send list to verify),
Thin film fuses, (F[size]…N or S or W TR),
Some leaded military parts (Send list to verify).

Other product families do not contain reportable Substances of Very High Concern (SVHC) as defined in Article 33 (1) & (2) "Substances of Very High Concern" EC Title VII, Chapter 1 Article 57 and revised as noted below.[1] In addition, AVX complies with the restrictions stated in Annex XVII of REACH.

In all cases, the lead substance is chemically combined in a ceramic or glass matrix and presents no hazard to humans or the environment under normal handling and use. Any excess or unused components may be returned to AVX for disposition at the customer's option. The above statements fulfill the communication requirements stated in REACH, Article 33.

Should you require further information or have any questions, please do not hesitate to contact avxrohs@avx.com

[1]Revisions to SVHC candidate list which have been reviewed in preparation of this statement:
9 October 2008
13 January 2010
30 March 2010
18 June 2010
15 December 2010
20 June 2011
19 December 2011
18 June 2012
19 December 2012
20 June 2013
16 December 2013
18 June 2014

[2]

DECLARATION LETTER FROM AOS

ALPHA & OMEGA SEMICONDUCTOR

Environmental Compliance Statement

Dear Valued Customers,

Alpha and Omega Semiconductor (Hong Kong) Ltd. (AOS) is committed to fully support our customers about the environmental and green production requirements. This statement reiterates our compliance with EU Directive 2002/95/EC and it's recasting EU Directive 2011/65/EU on the Restriction of the use of certain Hazardous Substances in electrical and electronic equipment (RoHS). The statement also shows our compliance with Sony Technical Standard SS-00259 about the Management regulations for the Environment-related Substances to be Controlled which are included in Parts and Materials.

AOS assures that our products are in compliance with the RoHS Directive, as well as SONY SS-00259. Specifically, our products do not contain the substances listed in the table below in concentrations more than the Maximum Concentration Value in homogeneous material except Note 1 specified.

Substance	Maximum Concentration Value (PPM)
Cadmium (Cd) and its compounds	75*
Lead (Pb) and its compounds	1000
Mercury (Hg) and its compounds	1000
Hexavalent Chromium (Cr^{6+}) and its compounds	1000
Polybrominated biphenyls (PBBs)	1000
Polybrominated diphenylethers (PBDEs)	1000

* The Maximum Concentration Value of Cd is 75 PPM in Denmark. RoHS requirement is 100 PPM.

Note 1: Lead contained in soft solder or solder paste (die attach material) which is used to assemble some parts within DPAK (TO252/TO251/TO251A), D2PAK (TO263/TO262), UltraSO8, TO220, TO220F, TO262F, DFN, QFN, SO8 Package Type, etc. The Exemption clause "7.a Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)." is applicable for such products.

Quality Assurance Department

Alpha and Omega Semiconductor (Hong Kong) Limited

11th January 2013

Quality Assurance Department

Declaration
Providing for limitations below, Alpha & Omega Semiconductor certifies that the information provided in this document is correct as of the date indicated on this page. The warranty provided herein shall be null and void if the information is revised in any format by any party without AOS's prior written authorization. In the event of any issues arising from information in this document, the warranty section of Alpha & Omega's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

DECLARATION LETTER FROM BROADCOM

RoHS EU Directive Compliance

Section 21.0

The European Union (EU) has adopted a new directive 2002/95/EC, the Restriction of Hazardous Substances ("RoHS Directive"), which will restrict the use of certain substances, including lead (Pb), in electrical and electronic products. The directive applies to all such electrical and electronic products and their component parts that will be placed on the market after July 1, 2006. In addition to lead, the directive restricts the use of mercury, cadmium, hexavalent chromium, and certain halide-containing flame retardants.

Broadcom Lead free parts are compliant to EU Restriction of Hazardous Substance (RoHS) Directive 2002/95/EC. The Lead-free package option is available today. Lead-free parts will have a letter 'G' added to the top line of the part marking. See example below

Broadcom standard (non "G") parts are compliant to 5/6 RoHS substances, exception being Pb.

Hg - Mercury Cd - Cadmium Cr+6 - Hexavalent Chromium PBB - Polybrominated Biphenyl PBDE - Polybrominated Diphenylether.

RoHS Compliant Part Marking

DECLARATION LETTER FROM WINBOND

winbond We Deliver

Halogen Free Compliance Report /不使用禁用物質證明書

PART NUMBER: W9812G6KH-6 **Document Date: Oct 22, 2013**

Winbond certifies that the above part number product is in compliance with Halogen Free (IEC 61249-2-21), European RoHS (EU Directive 2011/65/EU), China RoHS, and Level 1 of SONY SS-00259 requirements.

華邦保證以上產品型號符合無鹵素(IEC 61249-2-21), 歐盟RoHS指令(指令 2011/65/EU), 中國電子資訊產品污染控制管理辦法 及 索尼SS-00259第一級管理物質之規定

Banned Substance Analysis Result

Material	Pb	Cd	Hg	CrVI	PBB	PBDE	Br	Cl	Report Date	Analysis reports reference number
Mold Compound	<2	<2	<2	<2	<2	<2	<50	<50	Apr-13	CE/2013/41652
Die Attached (Material I)	<2	<2	<2	<2	<2	<2	<50	<50	Mar-13	CE/2013/23594
Leadframe (Material I)	<2	<2	<2	<2	<2	<2	NA	NA	Mar-13	CE/2013/23248
									Mar-13	CE/2013/23251
Leadframe(Material II)	<2	<2	<2	<2	<2	<2	NA	NA	Nov-12	KA/2012/A1658
									Nov-12	KA/2012/A1659
Plating or Solder Ball Composition	7.58	<2	<2	<2	<2	<2	NA	NA	Aug-13	KA/2013/81017
Bond Wire (Material I)	<2	<2	<2	<2	<2	<2	NA	NA	Nov-12	KA/2012/B1458
Chip	<2	<2	<2	<2	<2	<2	<50	<50	Nov-12	CE/2012/B2684

* **Unless otherwise noted, units are in PPM (parts-per-million)**

* **NA: Not applicable**

* **Third party analysis reports are available upon request through our sales representative**

* 如您需要進一步分析報告, 請聯絡本公司銷售代表

European Union's Restriction on Use of Hazardous Substances ("RoHS")

RoHS Restricted Substances	Threshold, Homogeneous Level
Cadmium (Cd)	< 100 ppm
Hexavalent Chromium (CrVI)	< 1000 ppm
Lead (Pb)	< 1000 ppm
Mercury (Hg)	< 1000 ppm
Polybrominated Biphenyls (PBBs)	< 1000 ppm
Polybrominated Diphenyl Ethers (PBDEs)	< 1000 ppm

Halogen Free Specifications (IEC 61249-2-21,JPCA-ES01 2003, IPC 4101)

Halogen Restricted Substances	Threshold, Homogeneous Level
Chlorine (Cl)	< 900 ppm
Bromine (Br)	< 900 ppm
Total concentration of Bromine (Br) +Chlorine (Cl)	< 1500 ppm

Signature: Jing Fong Tsai

Name/Title: **Jing-Fong Tsai**
Vice-President, Quality Assueance and ESH Center

winbond We Deliver

Halogen Free Compliance Report /不使用禁用物質證明書

PART NUMBER: W25Q64FVSSIG **Document Date: Jun 17, 2014**

Winbond certifies that the above part number product is in compliance with Halogen Free (IEC 61249-2-21), European RoHS (EU Directive 2011/65/EU), China RoHS, and Level 1 of SONY SS-00259 requirements.

華邦保證以上產品型號符合無鹵素(IEC 61249-2-21), 歐盟RoHS指令(指令 2011/65/EU), 中國電子資訊產品污染控制管理辦法 及 索尼SS-00259第一級管理物質之規定

Banned Substance Analysis Result

Material	Pb	Cd	Hg	CrVI	PBB	PBDE	Br	Cl	Report Date	Analysis reports reference number
Mold Compound (Material I)	<2	<2	<2	<2	<2	<2	<50	<50	Apr-14	KA/2014/41464
Mold Compound (Material II)	<2	<2	<2	<2	<2	<2	<50	<50	Apr-14	CE/2014/36576 CE/2014/36578
Die Attached (Material I)	<2	<2	<2	<2	<2	<2	<50	<50	Aug-13	CE/2013/80188 CE/2013/80191
Die Attached (Material II)	<2	<2	<2	<2	<2	<2	<50	<50	Aug-13	CE/2013/81075 CE/2013/81072 CE/2013/81077
Die Attached (Material III)	<2	<2	<2	<2	<2	<2	<50	<50	Oct-13	CE/2013/A3664
Leadframe	<2	<2	<2	<2	<2	<2	<50	NA	Apr-14	TWNC00368006
									Feb-14	KA/2014/20446
Tin Plating (Material I)	<7.58	<2	<2	<2	<2	<2	<50	NA	Aug-13	KA/2013/81017
Tin Plating (Material II)	<8	<2	<2	<2	<2	<2	<50	NA	Jan-14	CANEC1320406719
Bond Wire (Material I)	<2	<2	<2	<2	<2	<2	NA	NA	Nov-13	KA/2013/B0800
Bond Wire (Material II)	<2	<2	<2	<2	<2	<2	NA	NA	Nov-13	CE/2013/B1659
Chip	<2	<2	<2	<2	<2	<2	<50	<50	Nov-13	CE/2013/A4819

* Unless otherwise noted, units are in PPM (parts-per-million)
* NA: Not applicable
* Third party analysis reports are available upon request through our sales representative
* 如您需要進一步分析報告, 請聯絡本公司銷售代表

European Union's Restriction on Use of Hazardous Substances ("RoHS")

RoHS Restricted Substances	Threshold, Homogeneous Level
Cadmium (Cd)	< 100 ppm
Hexavalent Chromium (CrVI)	< 1000 ppm
Lead (Pb)	< 1000 ppm
Mercury (Hg)	< 1000 ppm
Polybrominated Biphenyls (PBBs)	< 1000 ppm
Polybrominated Diphenyl Ethers (PBDEs)	< 1000 ppm

Halogen Free Specifications (IEC 61249-2-21,JPCA-ES01 2003, IPC 4101)

Halogen Restricted Substances	Threshold, Homogeneous Level
Chlorine (Cl)	< 900 ppm
Bromine (Br)	< 900 ppm
Total concentration of Bromine (Br) +Chlorine (Cl)	< 1500 ppm

Signature: Jing Fong Tsai

Name/Title: **Jing-Fong Tsai**
Vice-President, Quality Assueance and ESH Center

DECLARATION LETTER SILICONLABS

SILICON LABS

Certificate of RoHS Compliance

June 30, 2013

Silicon Laboratories certifies that the device listed below is compliant with the European Union Directive 2011/65/EU for the Restriction of the use of certain Hazardous Substances in Electrical and Electronic Equipment (RoHS).

SI3402-A-GMR

No Lead (Pb), Cadmium (Cd), Mercury (Hg), Hexavalent Chromium (Cr+6), PBB or PBDE is intentionally added to this device. Any trace impurities of these substances contained in the part are below the RoHS specified threshold levels:

Cr+6, Hg, Pb, PBB's, PBDE's < 1000ppm
Cd < 100ppm

All information provided in this Certificate of Compliance is accurate, to the best of our knowledge, as of the date this certification was issued.

Sandeep P. Kumar

Sandeep P. Kumar
Vice President of Quality and Operations Engineering

DECLARATION LETTER FROM NXP

2010-07-01
Page 1 of 1 pages

CERTIFICATE OF COMPLIANCE
- RoHS Declaration -

NXP Semiconductors certifies that, to its best knowledge, semiconductor products designated to be:

- RoHS compliant (including all homogeneous sub-components – the pins, casing, internal parts) and meet the requirements of the EU-Directive 2002/95/EC (Restriction on Hazardous Substances, RoHS) and its amendments. This includes also the non use of DecaBromoDiphenylEther (Deca-BDE).

These semiconductor products can be recognized by the "RoHS compliant" logo on the box label. In addition, products that do not make use of a Lead exemption with the "Lead-free" logo. The intention is to make NXP products Lead-Free, when there is appropriate technology available and as long as there is no adverse effect on the NXP high quality standards.

Lead (Pb) is the last of the RoHS Substances to be removed since the other restricted substances were already not used in NXP semiconductor's products. NXP's term of "Lead-free" or "Pb-free" mean semiconductor products that are compatible with the current RoHS requirements for all six of the RoHS substances, including the requirement that Lead (Pb) does not exceed 1000ppm by weight, in all homogeneous subcomponent materials. Where designed to be soldered at high temperatures, NXP "Lead-free" products are suitable for use in specified "Lead-free" processes. This status is based on NXP's understanding of RoHS and NXP's knowledge of the materials that go into its products as of the date of disclosure of information.

To facilitate customer requirements to check compliance of the products of NXP Semiconductors, NXP has made the material content information available via the internet via: http://www.nxp.com/search/chemical_content/index.php

When reviewing the material content, a spreadsheet can be downloaded, for your convenience and further processing in chemical management systems like IMDS. Due to the availability of this service, it's NXP policy not to upload such material content data in customer systems.

The signature below verifies that statements above, including but not limited to any material composition data are, to the best of our knowledge, valid and accurate. However, NXP cannot warrant that products from NXP's customers, in which such NXP products are incorporated, will in turn comply with this RoHS Declaration.

NXP Semiconductors
Sustainability Office

Eric-Paul Schat
Senior Director & Sustainability Officer

NXP Semiconductors, Sustainability Office, High Tech Campus 60, 5656AG Eindhoven, The Netherlands
Tel: +31 40 27 28355, Fax: +31 27 29961, www.nxp.com

APPENDIX II

PHOTOGRAPHAS